

UNITED STATES PATENT AND TRADEMARK OFFICE  
**CERTIFICATE OF CORRECTION**

PATENT NO. : 7,095,226 B2  
APPLICATION NO. : 10/789682  
DATED : August 22, 2006  
INVENTOR(S) : Hong Wan et al.

Page 1 of 1

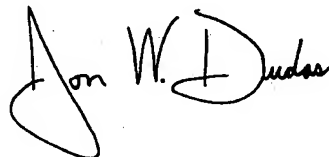
It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On the title page, at item [57], please delete: "Methods and apparatus for vertical chip-on-board sensor packages..." and replace with -- Methods and apparatus for vertical die chip-on-board sensor packages.... --

In claim 11, Column 14, line 14, please delete "alone" and substitute -- along --.

Signed and Sealed this

Eighteenth Day of September, 2007

A handwritten signature in black ink, appearing to read "Jon W. Dudas". The signature is stylized with a large, looping initial "J" and a distinct "D".

JON W. DUDAS  
*Director of the United States Patent and Trademark Office*